

/ Revised record

	! " #	\$! % & '	! () % * +	, -	. /
A	2016-5				
B	2019-4-20		0 1 2 3 4) 5 6 7 8 9 :	; < =	> ? @
C	2021-4-20	1	A B C D E F G 3 4 H I F G J K L M	N O P	> ? @
D	2021-10-16	4	Q R S T U V :	W X	> ? @

/ Descriptions

SOT-363 Y Z Z 2 [NPN \] ^ _ ` a M

Double silicon NPN transistor in a SOT-363 Plastic Package.

/ Features

b c d e f , g h MMDT5401 i j M F G k l M

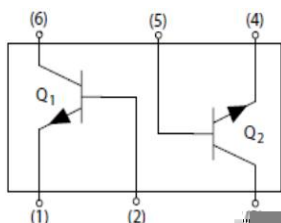
High voltage, complementary pair with MMDT5401. HF Product.

/ Applications

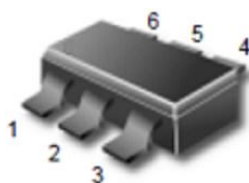
m n o p f e q r M

General purpose high voltage amplifier.

/ Equivalent Circuit



/ Pinning



PIN1 s 4 t Emitter

PIN 2 s 5 t Base

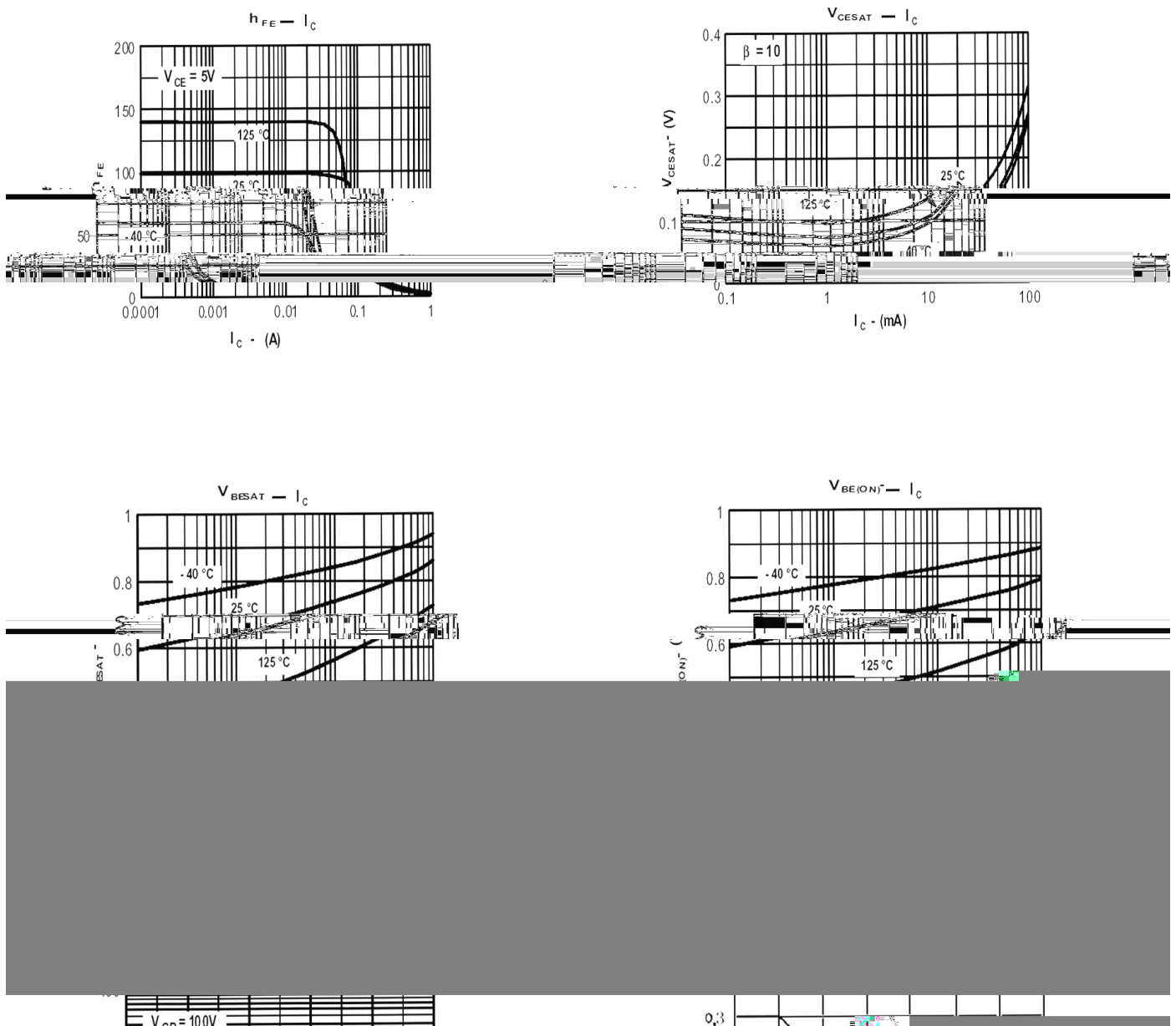
PIN 3 s 6 t Collector

/ h_{FE} Classifications & Marking

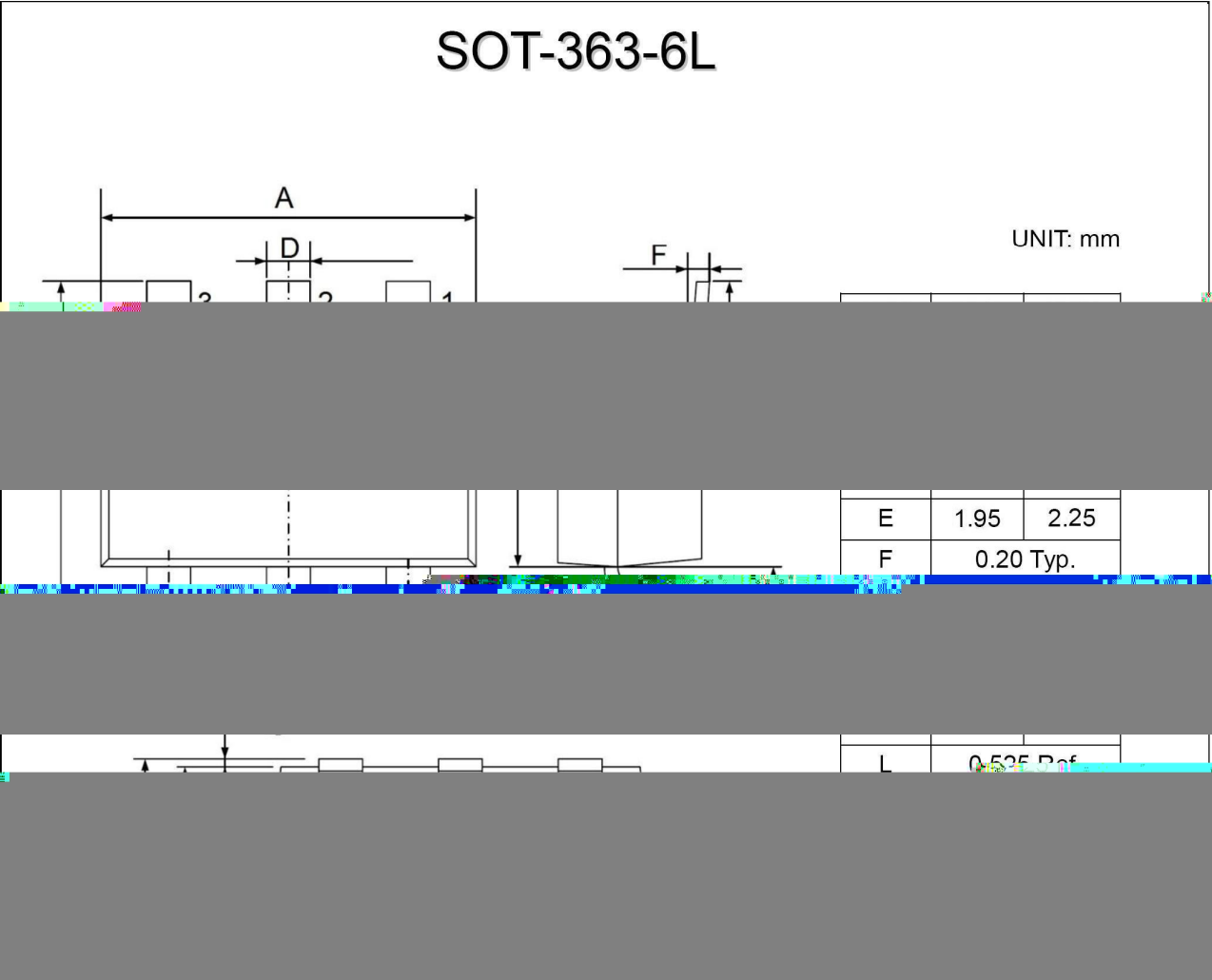
See Marking Instructions.

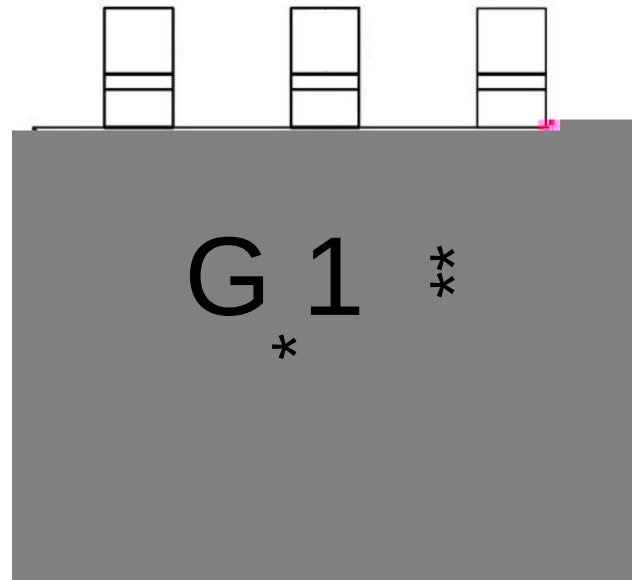
u v Parameter	w x Symbol	v y Rating	z { Unit
Collector to Base Voltage	V_{CBO}	180	V
Collector to Emitter Voltage	V_{CEO}		

/ Electrical Characteristic Curve



/ Package Dimensions



/ **Marking Instructions**

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● t " ©1^a «

G1 t " ¥ X ¬ '

***: $\mathbb{R}^k \times \mathbb{R}^k \rightarrow \mathbb{R}^k$

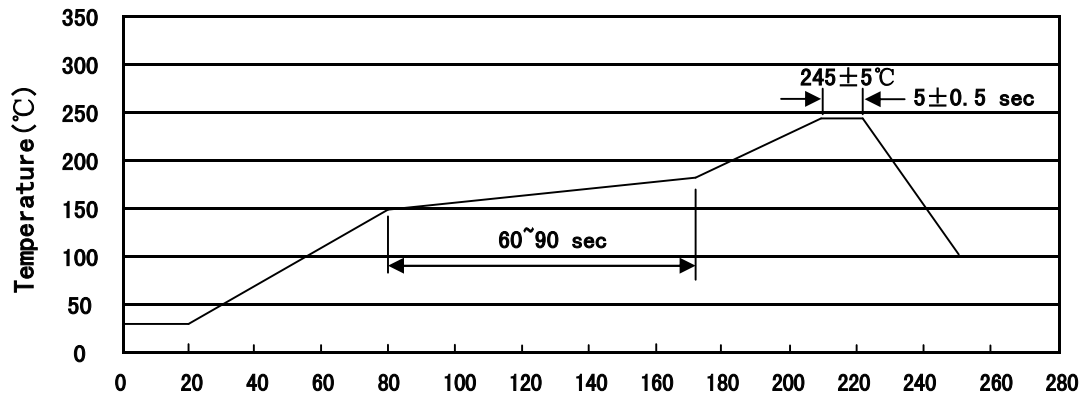
Note:

● t "1" Pin

G1 t	Product Type Code
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***: Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C

10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-363	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices